

JFP PP5 series



Manual & Semi Automatic DieBonder / Placer



The die bonder model PP5-4 is designed for accurate placement of delicate devices on substrate.

It achieves high accuracy placement using adjustable magnification optical device.

The machine provides for single collet vacuum pick and place of die from waffle pack, wafer, Gel-Pak or bulk die media and features adjustable and repeatable subsonic scrub. The placement accuracy is $< 5\mu\text{m}$, upon configuration.

A robust, and reliable mechanical concept, designed to be external vibration free.

Easy to use, flexible, the PP5-4 requires only minimum training to operate

DIE & SUBSTRATE

- Minimum die size 100*100 μm
- Maximum die size 25*25 mm long strip up to 80mm (more in option)
- Substrate handling, Up to 400x350 mm.

VISION SYSTEM

- Optical Zoom 10X, Magnification up to 180X
- CCD Color camera high resolution
- TFT monitor 17"
- Target generator
- Lighting
- Direct placement
- 2 references points for auto-centering placement
- Indexed Pick& Place Positioning

XY TABLE

- Motorized X 260mm, Y 120mm, x1 μm
- Vibration free
- Motion control with progressive joystick

PARAMETERS & DISPLAY

- LCD display
- Programmable force 10gr to 600 gr
- Programmable bond time
- Programmable scrub
- Indexed Pick and Placement mode
- Vacuum selectable

OPTIONS

- Dispenser
- Stamping
- UV
- Sorter: Eject system for wafer
- Eutectic
- Eutectic / Thermocompression

TECHNICAL SPECIFICATION

Power:	100 / 230VAC 500watt
Vacuum:	70%
Dimensions:	650*820*1450mm
Weight:	90kg.
Compressed Air	6 bar

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